

## P-Channel Enhancement Mode Power MOSFET

<p><b>Description</b></p> <p>The G26P04D5 uses advanced trench technology to provide excellent <math>R_{DS(ON)}</math>, low gate charge. It can be used in a wide variety of applications.</p> <p><b>General Features</b></p> <ul style="list-style-type: none"> <li>● <math>V_{DS}</math> -40 V</li> <li>● <math>I_D</math> (at <math>V_{GS} = -10V</math>) -26A</li> <li>● <math>R_{DS(ON)}</math> (at <math>V_{GS} = -10V</math>) &lt; 18mΩ</li> <li>● <math>R_{DS(ON)}</math> (at <math>V_{GS} = -4.5V</math>) &lt; 22mΩ</li> <li>● 100% Avalanche Tested</li> <li>● RoHS Compliant</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>● Power switch</li> <li>● DC/DC converters</li> </ul>	<p>Schematic diagram</p> <p>Marking and pin assignment</p> <p>DFN5*6-8L</p>		
<b>Device</b>	<b>Package</b>	<b>Marking</b>	<b>Packaging</b>
G26P04D5	DFN5*6-8L	G26P04	5000pcs/Reel

<b>Absolute Maximum Ratings</b> $T_C = 25^\circ C$ , unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-40	V
Continuous Drain Current	$I_D$	-26	A
Pulsed Drain Current (note1)	$I_{DM}$	-91	A
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Power Dissipation	$P_D$	50	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 To 150	$^\circ C$

<b>Thermal Resistance</b>			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	50	$^\circ C/W$
Thermal Resistance, Junction-to-Case	$R_{thJC}$	2.5	$^\circ C/W$

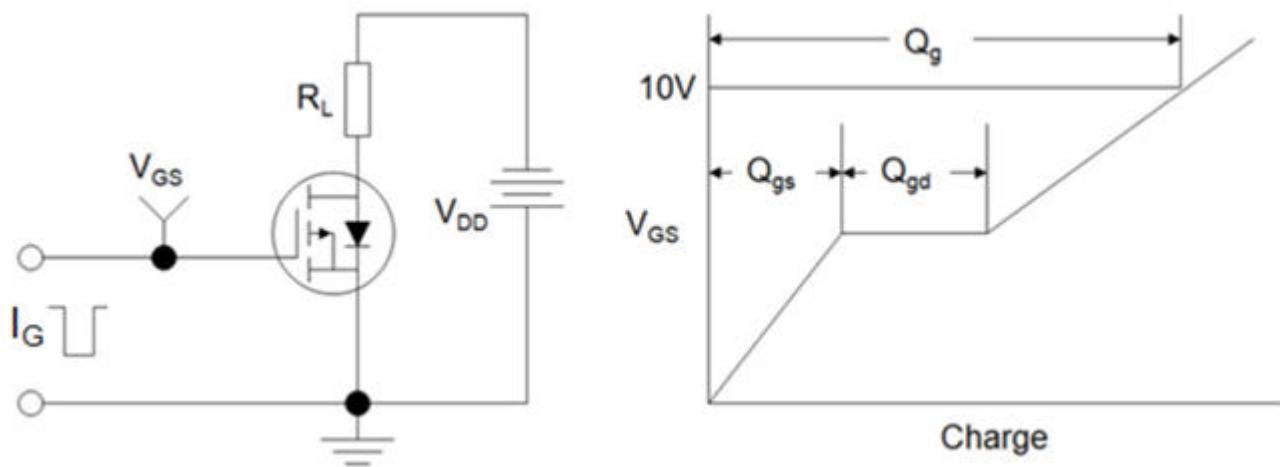
**Specifications**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-40	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = -40\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	-1	$\mu\text{A}$
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}$	--	--	$\pm 100$	$\text{nA}$
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1	-1.5	-2.5	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -12\text{A}$	--	15	18	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -12\text{A}$	--	18	22	
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}} = -5\text{V}, I_D = -12\text{A}$	--	28	--	S
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -20\text{V}, f = 1.0\text{MHz}$	--	2479	--	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		--	274	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	204	--	
Total Gate Charge	$Q_g$	$V_{\text{DD}} = -40\text{V}, I_D = -12\text{A}, V_{\text{GS}} = -10\text{V}$	--	45	--	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		--	6.1	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	10.1	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = -20\text{V}, I_D = -1\text{A}, R_G = 6\Omega$	--	9	--	$\text{ns}$
Turn-on Rise Time	$t_r$		--	7	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	78	--	
Turn-off Fall Time	$t_f$		--	39	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$	$T_C = 25^\circ\text{C}$	--	--	-26	A
Body Diode Voltage	$V_{\text{SD}}$	$T_J = 25^\circ\text{C}, I_F = I_S, V_{\text{GS}} = 0\text{V}$	--	--	-1.2	V

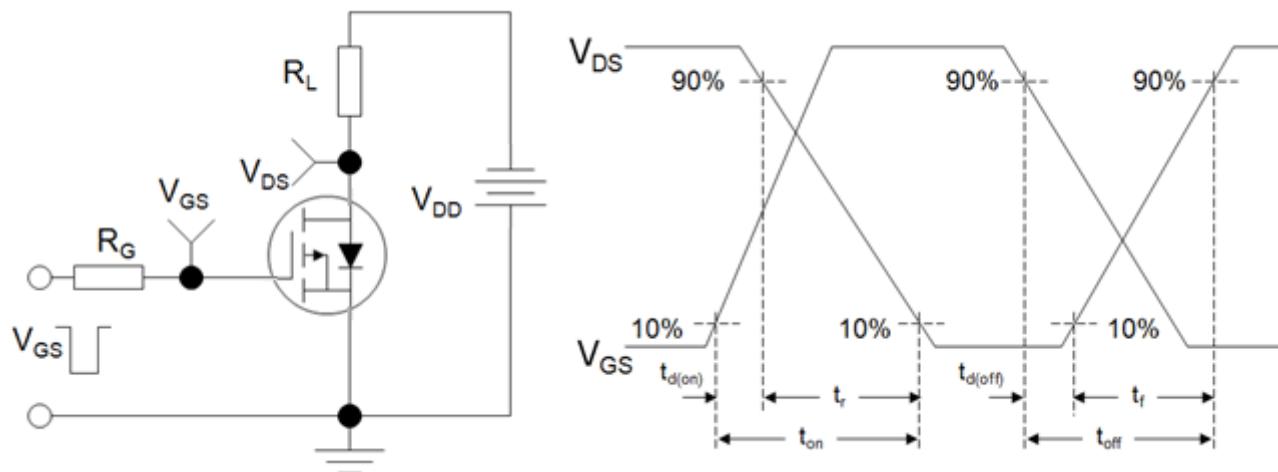
**Notes**

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Identical low side and high side switch with identical  $R_G$

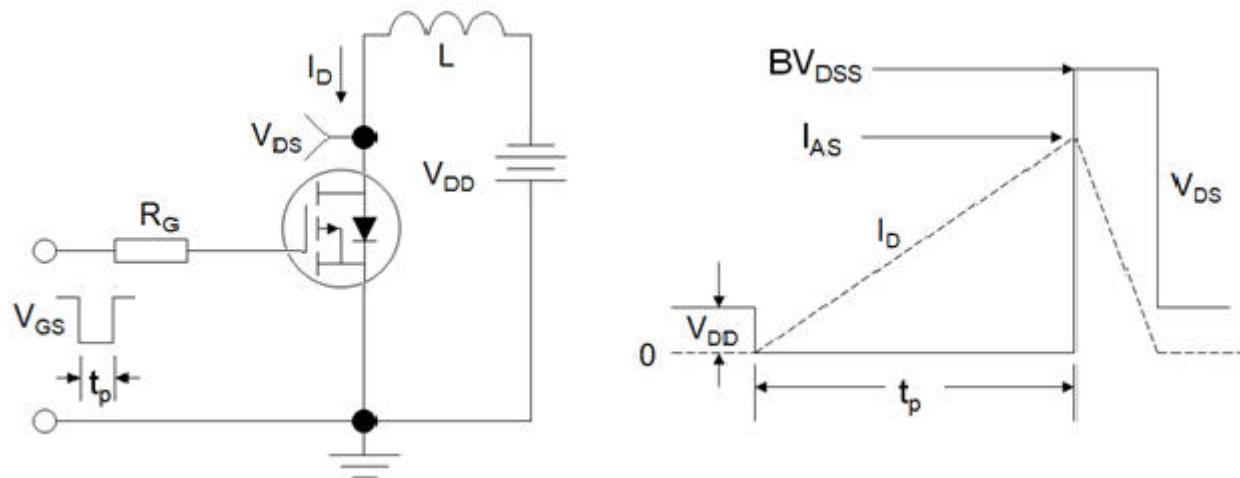
Gate Charge Test Circuit



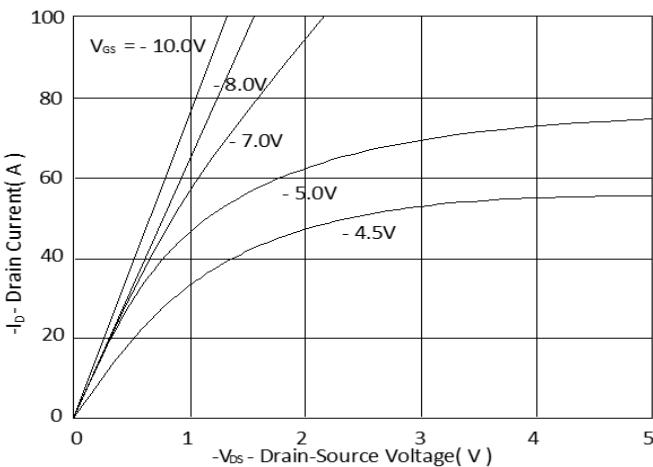
Switch Time Test Circuit



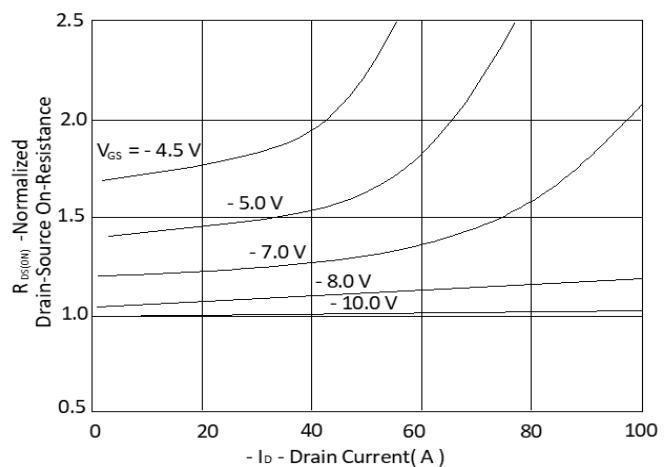
EAS Test Circuit



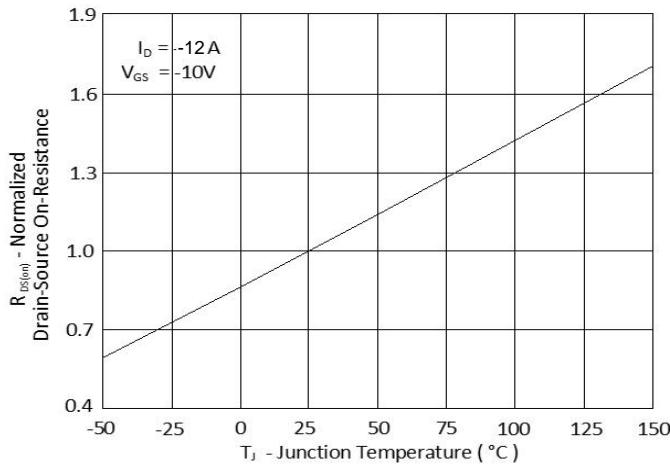
**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted



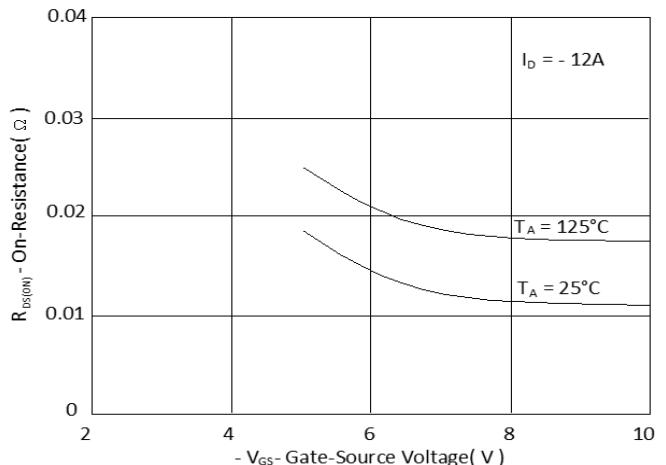
**Fig.1 Typical Output Characteristics**



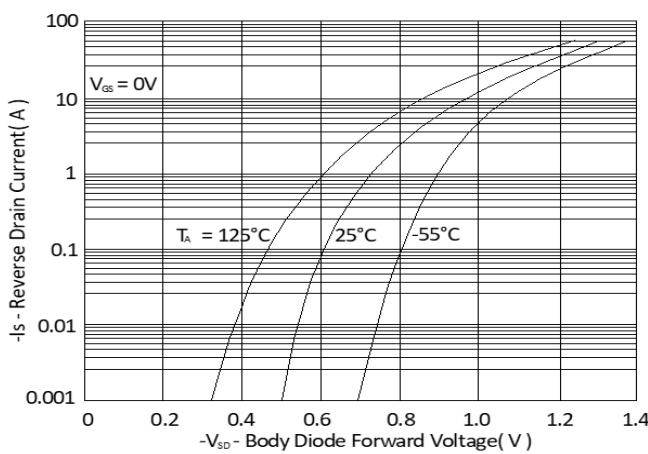
**Fig.2 On-Resistance Variation with Drain Current and Gate Voltage**



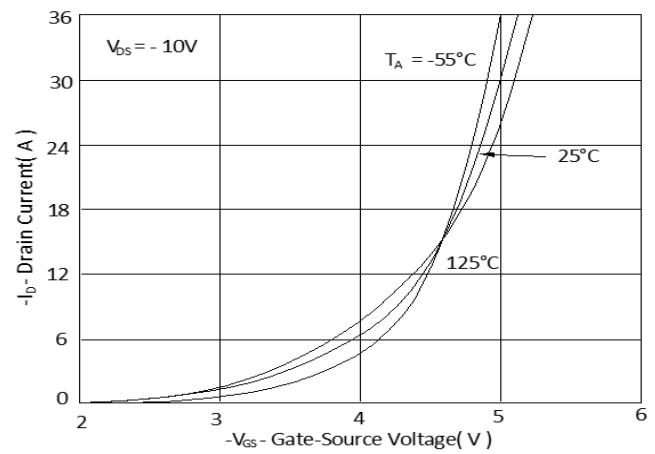
**Fig.3 Normalized On-Resistance v.s. Junction Temperature**



**Fig.4 On-Resistance v.s. Gate Voltage**

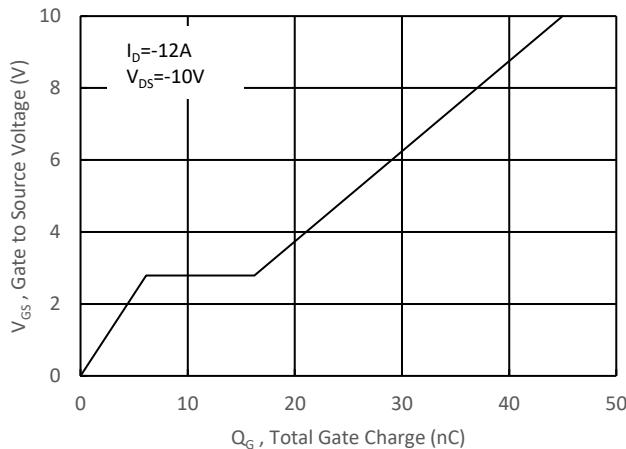


**Fig.5 Forward Characteristic of Reverse Diode**

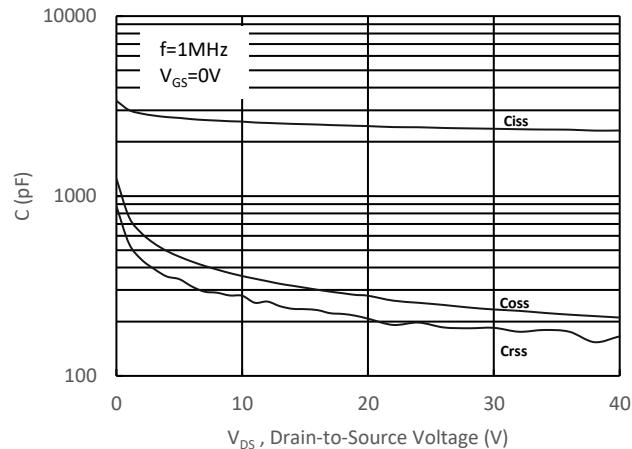


**Fig.6 Transfer Characteristics**

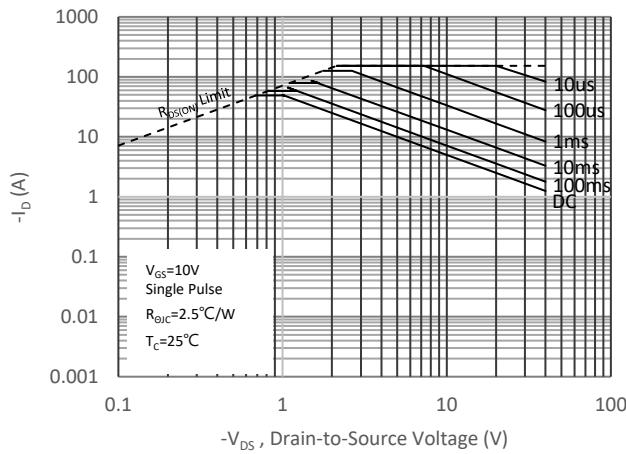
**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted



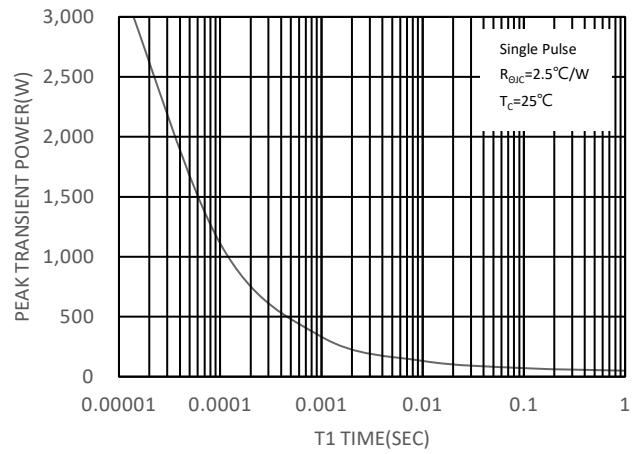
**Fig.7 Gate Charge Characteristics**



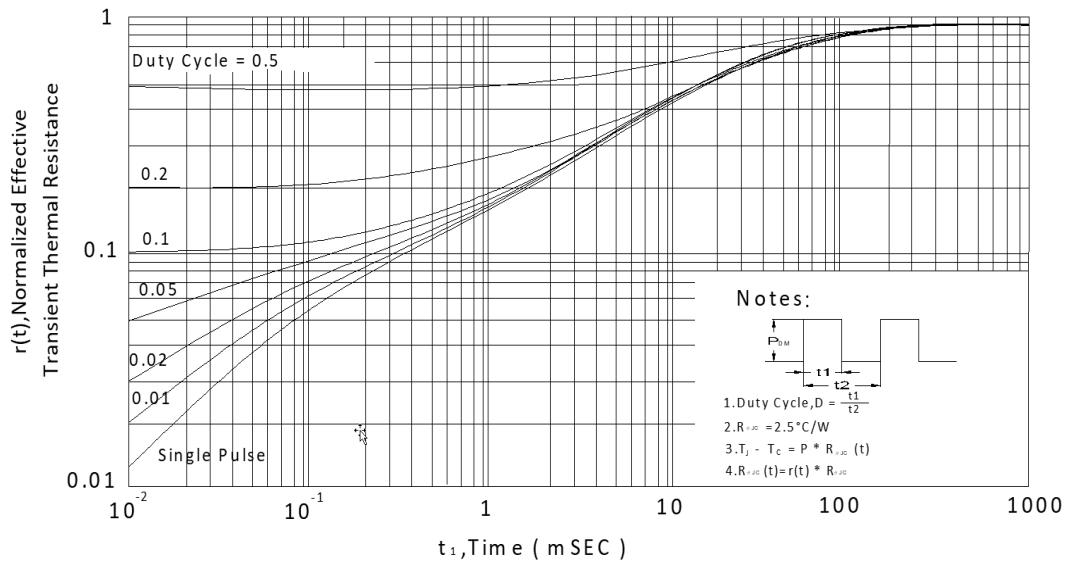
**Fig.8 Typical Capacitance Characteristics**



**Fig.9. Maximum Safe Operating Area**

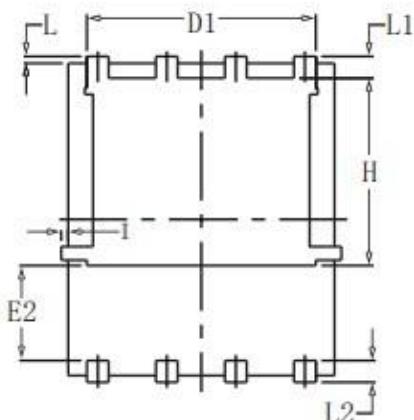
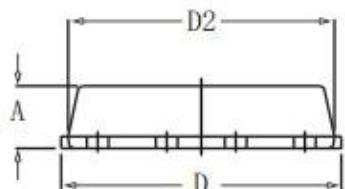
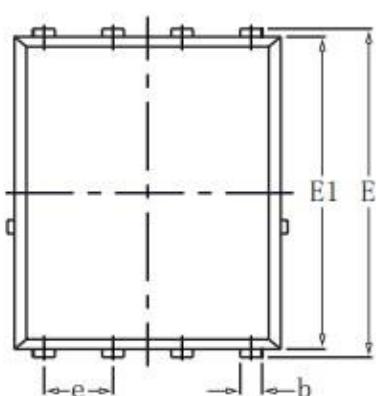


**Fig 10. Single Pulse Maximum Power Dissipation**



**Fig 11. Effective Transient Thermal Impedance**

## DFN5\*6-8L Package Information



SYMBOL	COMMON			
	MM		INCH	
	MIN	MAX	MIN	MAX
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.970	0.0324	0.0382
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.59	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	-	0.0630	-
e	1.27	BSC	0.05	BSC
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	-	0.18	-	0.0070